

We claim:

1. A method for preparing a patterned article comprising:
 - a) applying a release polymer to a portion of a substrate in a desired pattern;
 - 5 b) applying a substrate-adherent polymer over the pattern and over at least a portion of the substrate in a continuous layer having a substantially constant height with respect to the substrate; and
 - c) mechanically removing the substrate-adherent polymer from the pattern.
2. A method according to claim 1 wherein the release polymer has a surface energy less than that of the substrate-adherent polymer.
- 10 3. A method according to claim 1 wherein the release polymer comprises a fluoropolymer.
4. A method according to claim 1 wherein the substrate-adherent polymer comprises a polyimide.
5. A method according to claim 1 wherein the substantially constant height is less than about 15 μm .
- 15 6. A method according to claim 1 wherein the substantially constant height is about 3 μm to about 5 μm .
7. A method according to claim 1 wherein the substantially constant height is less than about 3 μm .
- 20 8. A method according to claim 1 wherein the release polymer pattern has a thickness and the substantially constant height is about 2 to about 10 times the release polymer pattern thickness.
9. A method according to claim 1 wherein the release polymer is applied using inkjet coating, die coating or screen coating.
- 25 10. A method according to claim 1 wherein the substrate-adherent polymer is applied using spin coating, dip coating, die coating or curtain coating.

12. A method according to claim 1 wherein the substrate-adherent polymer is removed from the pattern using impact media.

13. A method according to claim 1 wherein after the substrate-adherent polymer is removed from the pattern the pattern has at least one sidewall the major exposed portion of which is substantially perpendicular to the substrate.

14. A method according to claim 1 wherein the patterned article comprises a printed circuit board, electrical connector, information display or electronic component.

15. A method for preparing a patterned article comprising:

- a) applying a release polymer to a portion of a substrate in a desired pattern;
- b) applying a continuous layer of a substrate-adherent polymer over the pattern and over at least a portion of the substrate;
- c) applying an adhesive tape to the substrate-adherent polymer; and
- d) removing the adhesive tape and substrate-adherent polymer adhered to the tape while leaving a portion of the substrate-adherent polymer adhered to the substrate in a negative of the pattern.

16. A method according to claim 15 wherein the release polymer has a surface energy less than that of the substrate-adherent polymer.

17. A method according to claim 15 wherein the release polymer comprises a fluoropolymer.

18. A method according to claim 15 wherein the substrate-adherent polymer comprises a polyimide.

19. A method according to claim 15 wherein the continuous layer has a substantially constant height with respect to the substrate.

20. A method according to claim 19 wherein the substantially constant height is less than about 15 μm .

25 21. A method according to claim 19 wherein the substantially constant height is about 3 μm to about 5 μm .

22. A method according to claim 19 wherein the substantially constant height is less than about 3 μm .

23. A method according to claim 19 wherein the release polymer pattern has a thickness and the substantially constant height is about 2 to about 10 times the release polymer pattern thickness.

5 24. A method according to claim 19 wherein after removing the tape the pattern has at least one sidewall the major exposed portion of which is substantially perpendicular to the substrate.

25. A method according to claim 15 wherein the patterned article comprises a printed circuit board, electrical connector, information display or electronic component.

10 26. A method for preparing a patterned article comprising:

- a) applying a submicron-thickness release polymer layer to a portion of a substrate in a desired pattern;
- b) applying a continuous submicron-thickness polyimide layer over the pattern and over at least a portion of the substrate; and
- 15 c) removing a portion of the polyimide layer from the release polymer while leaving the remainder of the polyimide layer adhered to the substrate in a negative of the pattern.

27. A method according to claim 26 wherein the release polymer comprises a fluoropolymer.

28. A method according to claim 26 wherein the thickness of the polyimide layer is about 2 to about 10 times the release polymer layer thickness.

20 29. A method according to claim 26 wherein after removing the polyimide layer from the release polymer the pattern has at least one sidewall the major exposed portion of which is substantially perpendicular to the substrate.